Oak P V01.20   July 2009

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1. Overview, Statistics

1.1. PCB

PCB type	rigid
Insulator material	FR4
Board Size Extents	45 X 12 mm (final size)
Layer Count	2
Board thickness	1.6mm
Copper thickness	35µm
Hole Count	40
Solder mask	on both sides
Silkscreen	no
Surface	HAL Pb-free

1.2. Statistics

Through Holes	53
Minimum line width	0.15mm
Smallest drill diameter	0.3mm
Smallest annular ring	0.15mm
Minimum spacing	0.15mm

1.3. Assembly

Assembly sides: SMD components on top side

SMD component count   10

THT component count   –

 Pin Count   114

2. Layer Stackup

2.1. Sequence of the Gerber Files

Please stack the layers in the order given below:

File name	Description	Format
SoldermaskTop.gdo	*Solder mask (component side)*	RS274-X
EtchLayer1Top.gdo	top layer / component side	
EtchLayer2Bottom.gdo	bottom layer / solder side	RS274-X
SoldermaskBottom.gdo	*Solder mask (solder side)*	

2.2. Additional Files

SolderPasteTop.gdo	Solder Paste (component side)	RS274-X
Mechanics.gdo	Mechanical dimensions	RS274-X
ThruHoleNonPlated.ncd	Drill coordinates (plated)	NC drill
ThruHolePlated.ncd	Drill coordinates (non-plated)	NC drill
ContourPlated.ncd	Milling coordinates (non-plated)	NC drill

2.3. Layer thickness

The total thickness of the board must be 1.7mm±0.1mm
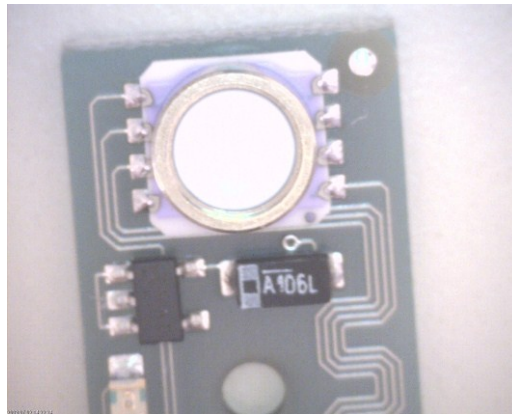
Proposed thicknesses:

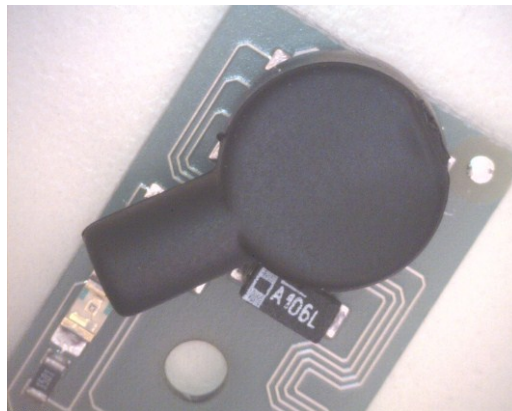|	Description	Material	Thickness
	Top Solder Mask		
1	Top Layer	Cu	35u
		Core	1600u
4	Bottom Layer	Cu	35u
	Bottom Solder Mask		
Overall thickness			1.7mm

3. Sensor Protection Cap Mounting Instructions

After the soldering process, the sensor protection cab has to be mounted according to the following images. There is no need for a tool.

Figure 1 Oak G without protection cap

Figure 2 Oak G with mounted cap

Disclaimer: